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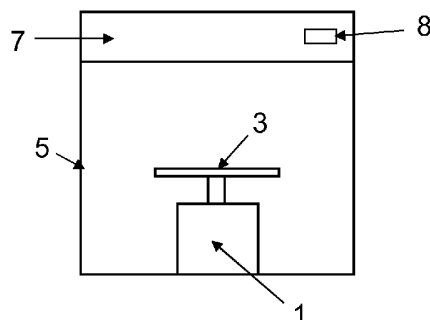


FIG. 1

(57) Abstract: A semiconductor wafer mass metrology apparatus comprising: a measurement chamber for measuring the weight and/or the mass of a semiconductor wafer; a first temperature changing part for changing a temperature of the semiconductor wafer before the semiconductor wafer is transported into the measurement chamber; and a first temperature sensor for sensing a first temperature, wherein the first temperature is: a temperature of the first temperature changing part; or a temperature of the semiconductor wafer when the semiconductor wafer is on the first temperature changing part, or when the semiconductor wafer leaves the first temperature changing part.



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